



Material Composition Declaration

Package Information

Package	Package Weight (mg)	Terminal Finish	MSL Rating
SOT-523	2	Matte Tin (Sn)	1

Product Group

Type No.	Description
RB715W	Diode Schottky 30mA 40V
BAS70T / AT / CT / ST	Diode Schottky 70mA 70V
RB548W	Diode Schottky 100mA 30V
BAT54T / AT / CT / ST	Diode Schottky 200mA 30V
BAS40T / AT / CT / ST	Diode Schottky 200mA 40V
DA221	Diode Switching 100mA 20V
DAN222, DAP222	Diode Switching 100mA 80V
BAV70T, BAV99T, BAW56T	Diode Switching 200mA 75V
BAS16T	Diode Switching 200mA 100V
BAS21T	Diode Switching 200mA 250V
MMBD4448HT / HTA / HTC / HTS	Diode Switching 250mA 80V

Component	Material	Substance	CAS No.	Material Mass (%)	Material Mass (mg)	Component Mass (%)	Component Mass (mg)	PPM
Die	Doped Silicon*	Si	7440-21-3	100.00	0.026	1.29	0.026	13000
Wire Bond	Gold	Au	7440-57-5	100.00	0.003	0.13	0.003	1500
Leadframe	Ferrous Alloy	Fe	7439-89-6	56.40	0.405	35.92	0.718	202476
		Ni	7440-02-0	42.00	0.302			150780
		Mn	7439-96-5	0.80	0.006			2872
		Co	7440-48-4	0.50	0.004			1795
		Si	7440-21-3	0.30	0.002			1077
Die Bond	Silver Silicone	Ag	7440-22-4	80.00	0.013	0.81	0.016	6400
		Bisphenol F	28064-14-4	15.00	0.002			1200
		Glycidyl neodeconate	26761-45-5	5.00	0.001			400
Plating	Matte Tin	Sn	7440-31-5	100.00	0.036	1.81	0.036	18000
Encapsulation	EMC	Silica	7631-86-9	79.00	0.949	60.04	1.201	474395
		Epoxy Resin	29690-82-2	20.00	0.240			120100
		Carbon Black	1333-86-4	1.00	0.012			6005

Tolerance ±10%

*Dopant and metallization of the silicon die are not reported in this statement where their concentration is less than the minimum reportable level per EIA JIG-101.

Data disclosed herewith is approximate and is based on information from suppliers surveys, Material Safety Datasheet, engineering calculations and measurements. Won-Top Electronics(WTE) has checked all information carefully and believes it to be correct and accurate. However, WTE cannot assume any responsibility for inaccuracies. WTE reserves the right to change any or all information herein without further notice.

RoHS Declaration

The European Parliament and of the Council on the Restriction of the use of Certain Hazardous Substances in Electrical and Electronics Equipment (RoHS) directive restricts the concentration of Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBD) to 0.1%(1000 PPM) and restricts the concentration of Cadmium (Cd) to 0.01%(100 PPM) in homogeneous materials of electronics products.

The product group listed above and the homogenous materials are compliant with the Directive 2011/65/EU. WTE warrants that all its packing, components and/or products supplied to the Customer and/or its affiliated companies or designated contractors do not contain these hazardous substances in quantity levels higher than or equal to the thresholds to this directive.

Exemptions as declared for the directive are:

- 7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).
- 7(c)-I Lead in glass (applicable for glass passivated silicon die).